

# MECHANICAL CASE OUTLINE

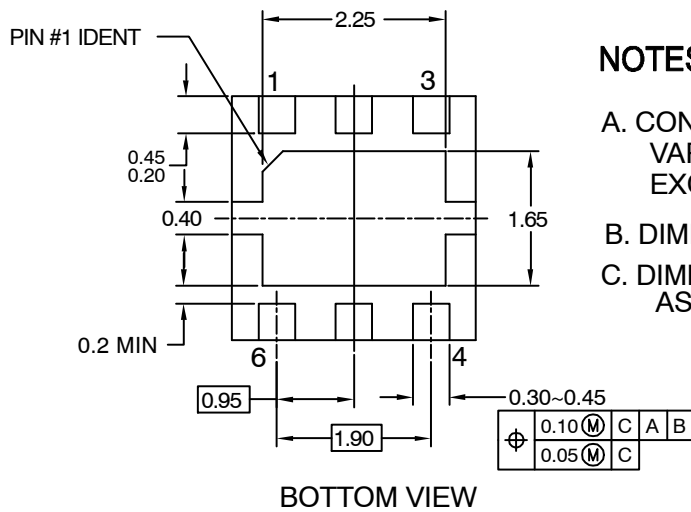
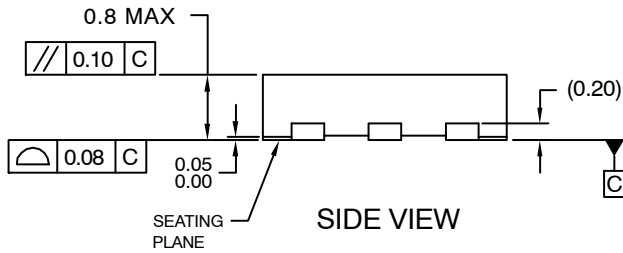
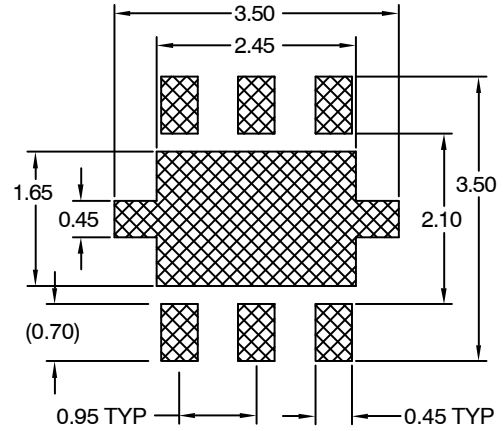
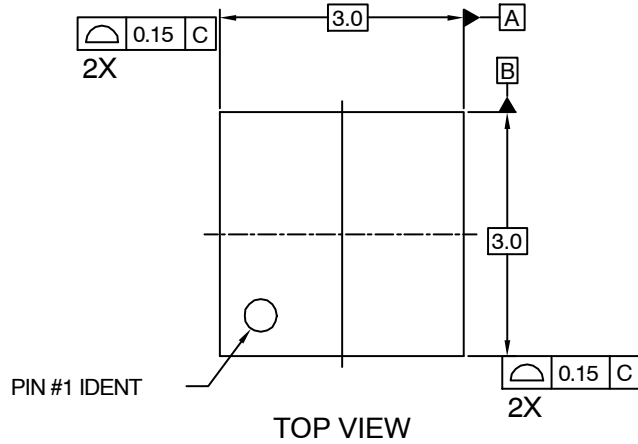
## PACKAGE DIMENSIONS

ON Semiconductor®



WDFN6 3x3, 0.95P  
CASE 511CQ  
ISSUE O

DATE 31 JUL 2016



### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION WEEA, DATED 11/2001 EXCEPT FOR DAP EXTENSION TABS
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

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